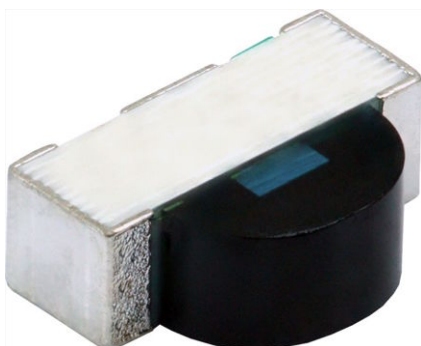




## Silicon PIN Photodiode



## DESCRIPTION

VEMD10940F is a high speed and high sensitive PIN photodiode in a miniature side looking, surface mount package (SMD) with daylight blocking filter. Filter is matched with IR emitters operating at wavelength of 830 nm to 950 nm. The photo sensitive area of the chip is 0.23 mm<sup>2</sup>.

## FEATURES

- Package type: Surface mount
- Package form: Side view
- Dimensions (L x W x H in mm): 3 x 2 x 1
- High radiant sensitivity
- Daylight blocking filter matched with 830 nm to 950 nm IR emitters
- Fast response times
- Angle of half sensitivity:  $\varphi = \pm 75^\circ$
- Package matched with IR emitter VSMB10940 and VSMG10850
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



## APPLICATIONS

- High speed photo detector
- Infrared remote control
- Infrared data transmission
- Photo interrupters
- IR touch panels

## PRODUCT SUMMARY

COMPONENT	$I_{ra}$ (μA)	$\varphi$ (deg)	$\lambda_{0.5}$ (nm)
VEMD10940F	3	$\pm 75$	780 to 1050

## Note

- Test conditions see table "Basic Characteristics"

## ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMD10940F	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view

## Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	60	V
Power dissipation	$T_{amb} \leq 25^\circ\text{C}$	$P_V$	104	mW
Junction temperature		$T_j$	100	$^\circ\text{C}$
Operating temperature range		$T_{amb}$	- 40 to + 100	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	- 40 to + 100	$^\circ\text{C}$
Soldering temperature	Acc. reflow solder profile fig. 7	$T_{sd}$	260	$^\circ\text{C}$
Thermal resistance junction/ambient	Acc. J-STD-051	$R_{thJA}$	450	K/W



BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 50\text{ mA}$	$V_F$		1		V
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$ , $E = 0$	$V_{(BR)}$	32			V
Reverse dark current	$V_R = 10\text{ V}$ , $E = 0$	$I_{ro}$		1	10	nA
Diode capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$	$C_D$		4		pF
	$V_R = 5\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$	$C_D$		1.3		pF
Open circuit voltage	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$	$V_o$		350		mV
Temperature coefficient of $V_o$	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$	$TK_{V_o}$		- 2.6		mV/K
Short circuit current	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$	$I_k$		3		$\mu\text{A}$
Temperature coefficient of $I_k$	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$	$TK_{I_k}$		0.1		%/K
Reverse light current	$E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$ , $V_R = 5\text{ V}$	$I_{ra}$	2	3	4	$\mu\text{A}$
Angle of half sensitivity		$\varphi$		$\pm 75$		deg
Wavelength of peak sensitivity		$\lambda_p$		920		nm
Range of spectral bandwidth		$\lambda_{0.5}$		780 to 1050		nm
Rise time	$V_R = 10\text{ V}$ , $R_L = 1\text{ k}\Omega$ , $\lambda = 820\text{ nm}$	$t_r$		100		ns
Fall time	$V_R = 10\text{ V}$ , $R_L = 1\text{ k}\Omega$ , $\lambda = 820\text{ nm}$	$t_f$		100		ns

### BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

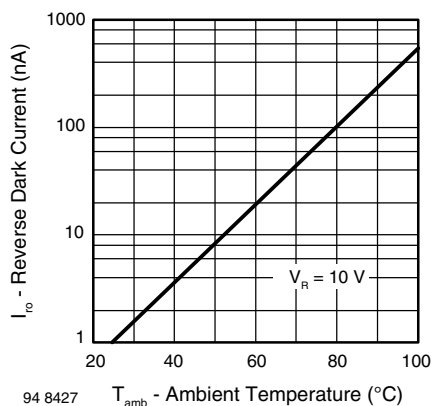


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

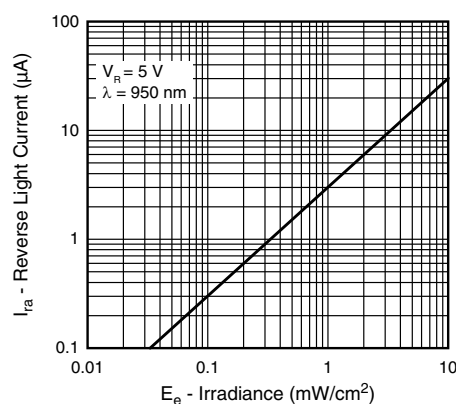


Fig. 3 - Reverse Light Current vs. Irradiance

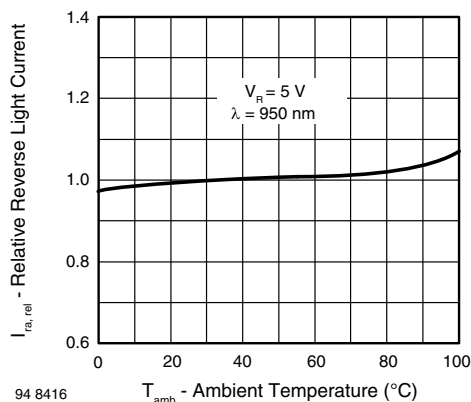


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

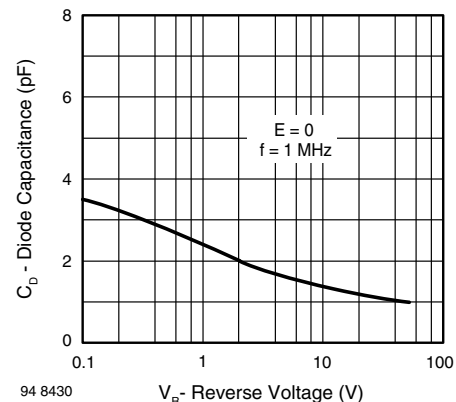


Fig. 4 - Diode Capacitance vs. Reverse Voltage

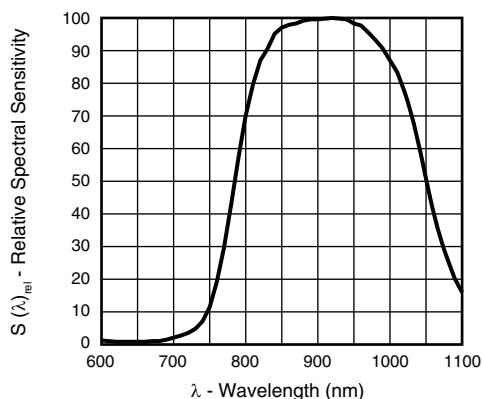


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

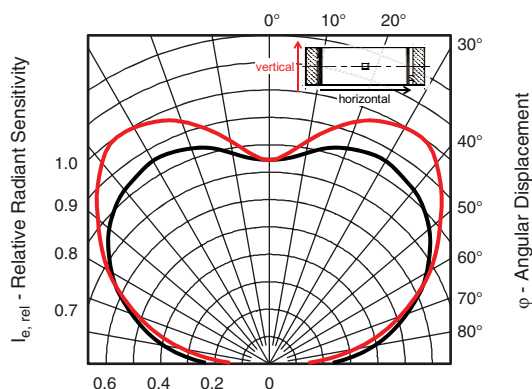


Fig. 6 - Relative Radiant Sensitivity vs. Angular Displacement

## REFLOW SOLDER PROFILE

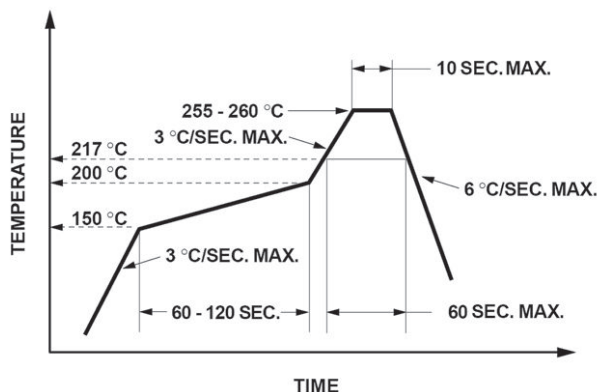


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions:  $T_{amb} < 30^{\circ}\text{C}$ ,  $RH < 60\%$

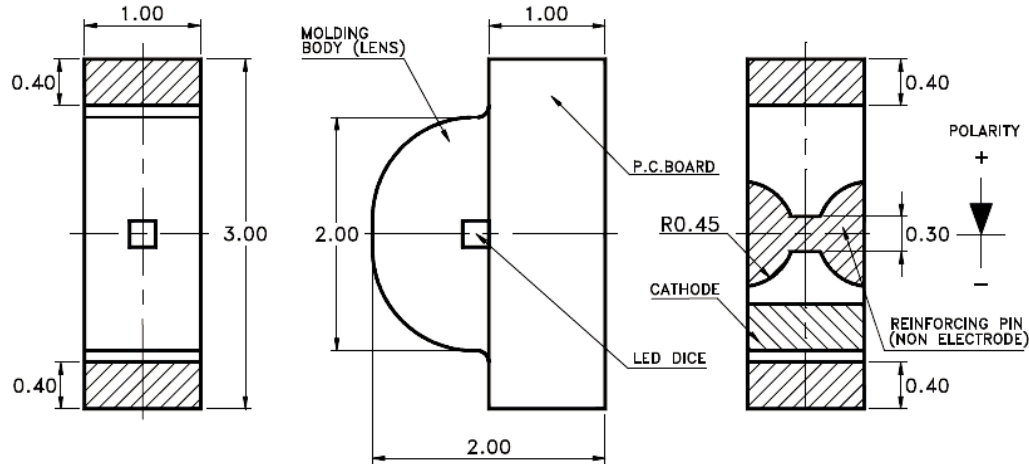
Moisture sensitivity level 3, acc. to J-STD-020.

## DRYING

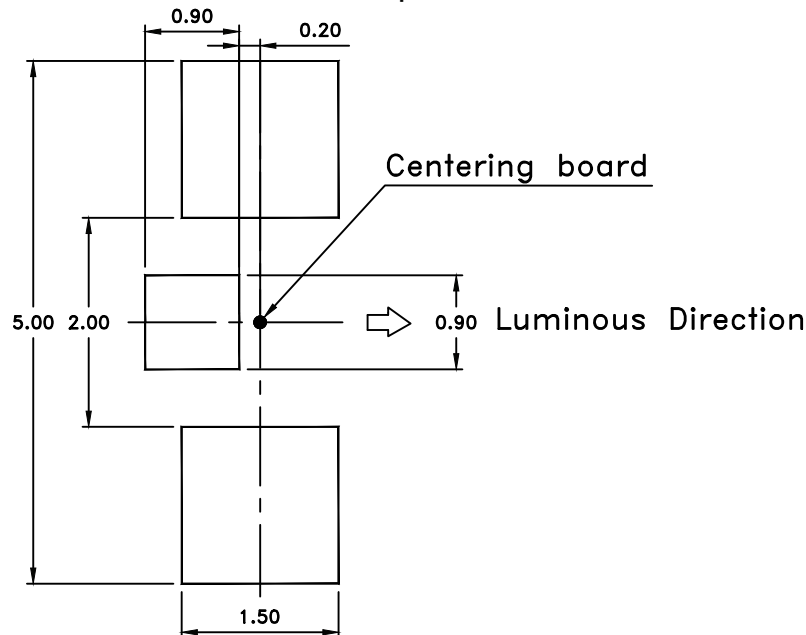
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at  $40^{\circ}\text{C} (+ 5^{\circ}\text{C})$ ,  $RH < 5\%$ .



**PACKAGE DIMENSIONS** in millimeters: **VEMD10940F**

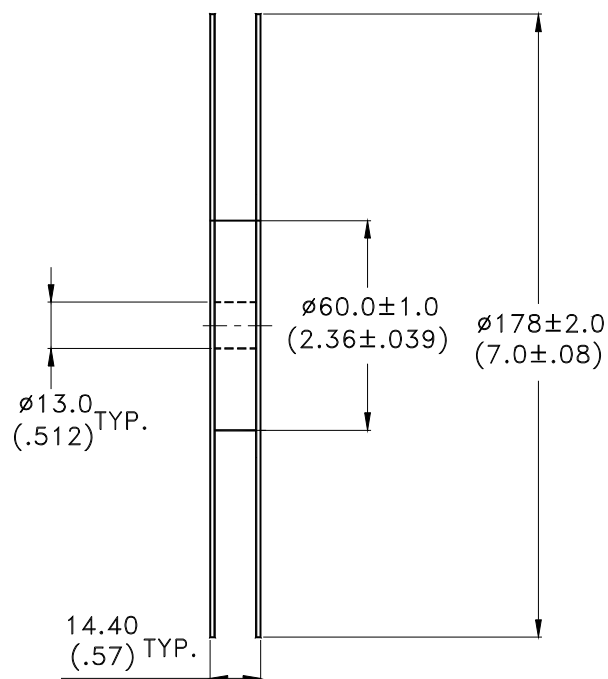
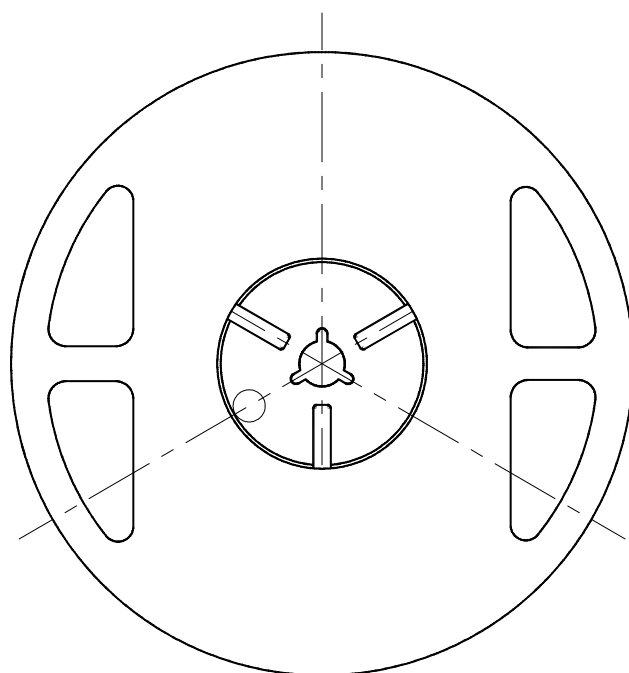
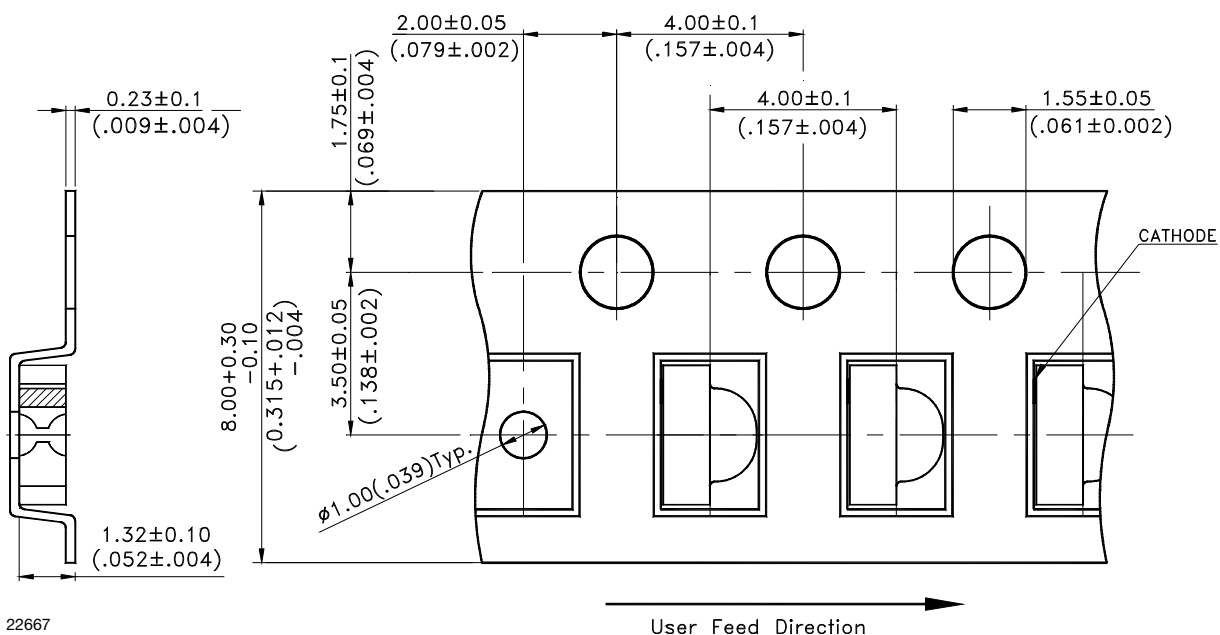


**Recommended Solder Pad Footprint**



22701

**TAPING AND REEL DIMENSIONS** in millimeters: **VEMD10940F**





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